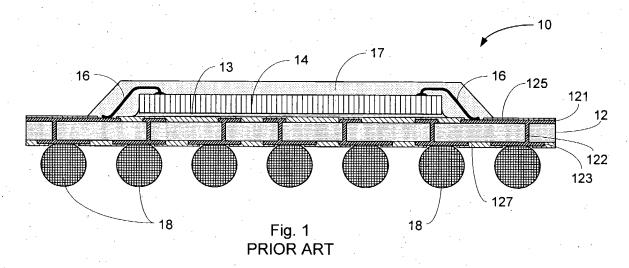
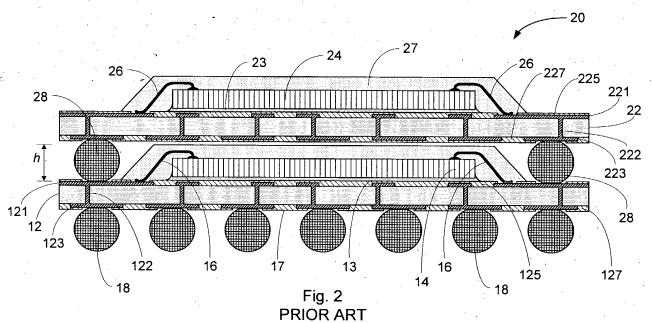
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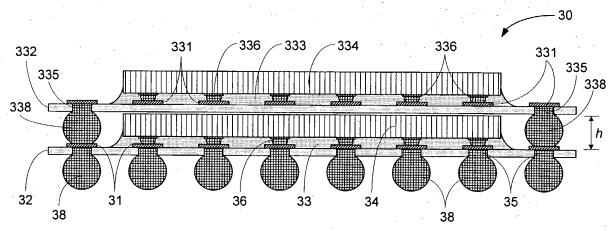
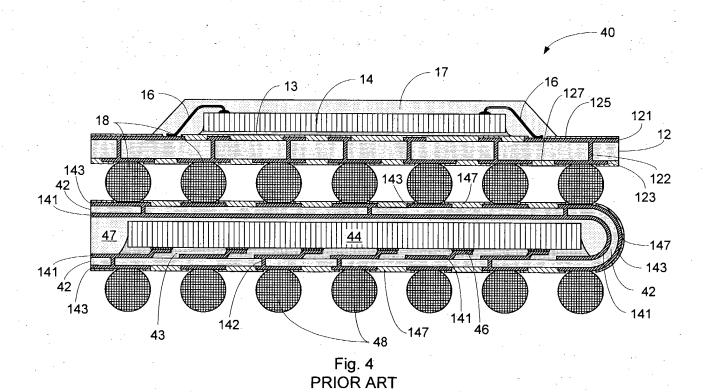
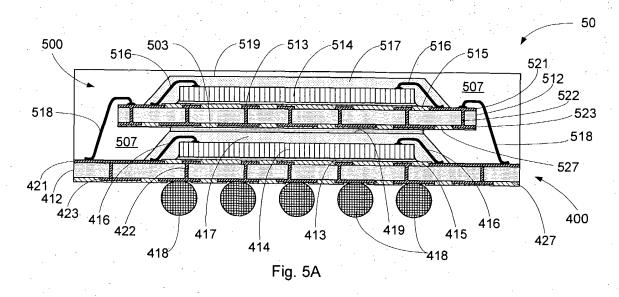


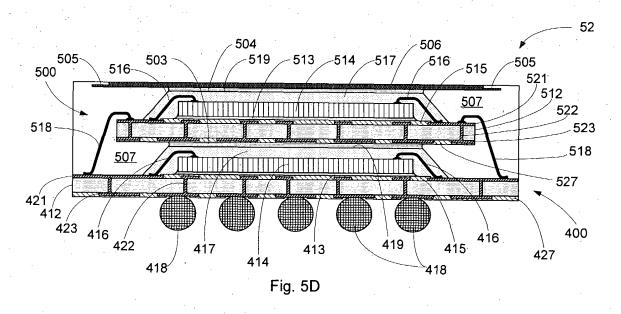
Fig. 3 PRIOR ART

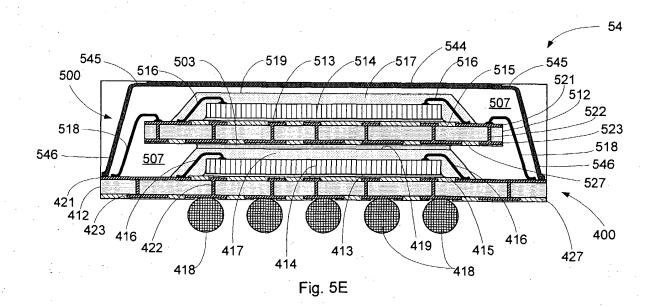


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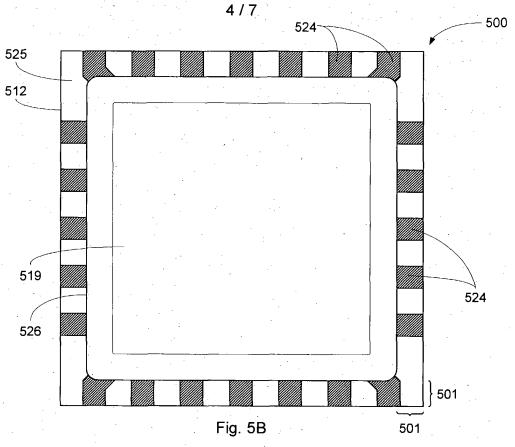
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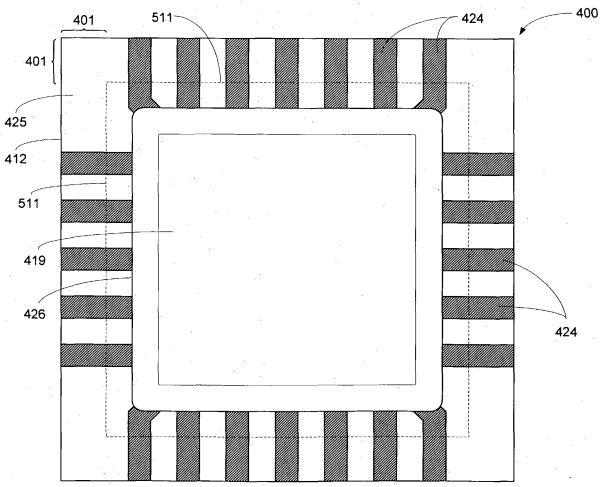
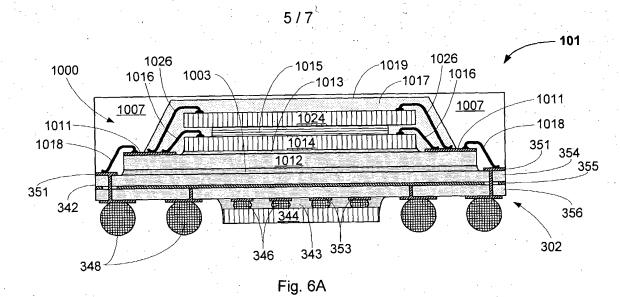
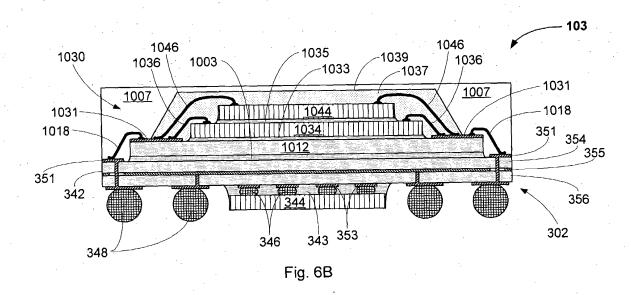
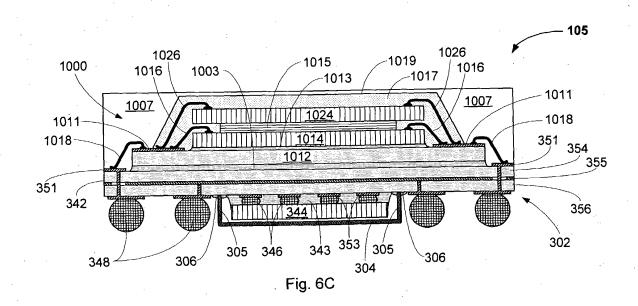


Fig. 5C

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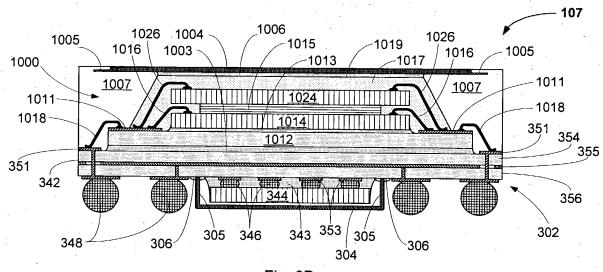






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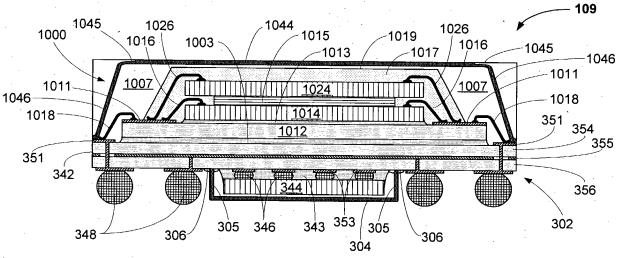


Fig. 6E

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